

FGW25N120WD

Discrete IGBT

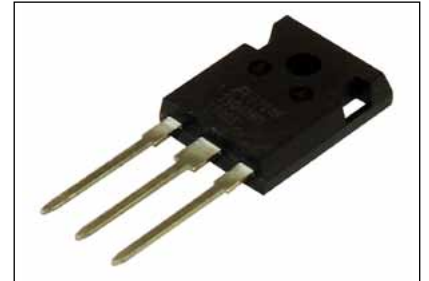
Discrete IGBT (High-Speed W series) 1200V / 25A

■ Features

- Low power loss
- Low switching surge and noise
- High reliability, high ruggedness (RBSOA, SCSOA etc.)

■ Applications

- Uninterruptible power supply
- PV Power conditioner
- Inverter welding machine



■ Maximum Ratings and Characteristics

● Absolute Maximum Ratings (at $T_c=25^\circ\text{C}$ unless otherwise specified)

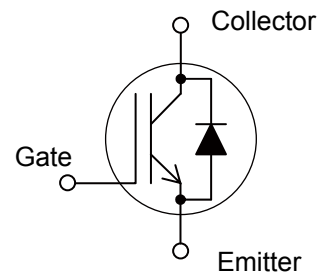
Items	Symbols	Characteristics	Units	Remarks
Collector-Emitter voltage	V_{CES}	1200	V	
Gate-Emitter voltage	V_{GES}	± 20	V	
DC Collector Current	$I_{C@25}$	40	A	$T_c=25^\circ\text{C}$, $T_j=150^\circ\text{C}$
	$I_{C@100}$	25	A	$T_c=100^\circ\text{C}$, $T_j=150^\circ\text{C}$
Pulsed Collector Current	I_{CP}	100	A	Note *1
Turn-Off Safe Operating Area	-	100	A	$V_{CE} \leq 1200\text{V}$, $T_j \leq 175^\circ\text{C}$
Diode Forward Current	$I_{F@25}$	22	A	
	$I_{F@100}$	12	A	
Diode Pulsed Current	I_{FP}	100	A	Note *1
Short Circuit Withstand Time	t_{SC}	5	μs	$V_{CC} \leq 600\text{V}$, $V_{GE} = 15\text{V}$ $T_j \leq 150^\circ\text{C}$
IGBT Max. Power Dissipation	P_{D_IGBT}	270	W	$T_c=25^\circ\text{C}$
FWD Max. Power Dissipation	P_{D_FWD}	75	W	$T_c=25^\circ\text{C}$
Operating Junction Temperature	T_j	$-40 \sim +175$	$^\circ\text{C}$	
Storage Temperature	T_{stg}	$-55 \sim +175$	$^\circ\text{C}$	

Note *1 : Pulse width limited by T_{jmax} .

● Electrical characteristics (at $T_j=25^\circ\text{C}$ unless otherwise specified)

Description	Symbols	Conditions		Characteristics			Unit
				min.	typ.	max.	
Zero Gate Voltage Collector Current	I _{CES}	V _{CE} = 1200V, V _{GE} = 0V	T _J =25°C	-	-	250	μA
			T _J =175°C	-	-	2	mA
Gate-Emitter Leakage Current	I _{GES}	V _{CE} = 0V, V _{GE} = ±20V		-	-	200	nA
Gate-Emitter Threshold Voltage	V _{GE (th)}	V _{CE} = 20V, I _C = 25mA		5.0	6.0	7.0	V
Collector-Emitter Saturation Voltage	V _{CE (sat)}	V _{GE} = 15V, I _C = 25A	T _J =25°C	1.4	2.0	2.6	V
			T _J =175°C	-	2.6	-	
Input Capacitance	C _{ies}	V _{CE} =25V		825	1650	2475	pF
Output Capacitance	C _{oes}	V _{GE} =0V		37	75	113	
Reverse Transfer Capacitance	C _{res}	f=1MHz		11	23	35	
Gate Charge	Q _G	V _{CC} = 400V I _C = 25A V _{GE} = 15V		40	80	120	nC
Turn-On Delay Time	t _{d(on)}	T _J = 25°C		14	28	42	ns
Rise Time	t _r	V _{CC} = 600V		16	32	48	
Turn-Off Delay Time	t _{d(off)}	I _C = 25A		61	122	183	
Fall Time	t _f	V _{GE} = 15V		16	32	48	
Turn-On Energy	E _{on}	R _G = 10Ω		0.45	0.9	1.35	mJ
Turn-Off Energy	E _{off}	L = 500μH Energy loss include “tail” and FWD (FDRW12S120J) reverse recovery.		0.65	1.3	1.95	
Turn-On Delay Time	t _{d(on)}	T _J = 150°C		14	28	42	ns
Rise Time	t _r	V _{CC} = 600V		16	32	48	
Turn-Off Delay Time	t _{d(off)}	I _C = 25A		89	178	267	
Fall Time	t _f	V _{GE} = 15V		30	60	90	
Turn-On Energy	E _{on}	R _G = 10Ω		0.75	1.5	2.25	mJ
Turn-Off Energy	E _{off}	L = 500μH Energy loss include “tail” and FWD (FDRW12S120J) reverse recovery.		1.1	2.2	3.3	
Forward Voltage Drop	V _F	I _F =12A	T _J =25°C	1.3	2.2	2.8	V
			T _J =175°C	1.0	1.8	2.6	V
Diode Reverse Recovery Time	t _{rr1}	V _{CC} =30V I _F = 1.2A -di/dt=200A/μs		16.5	33	42	ns
Diode Reverse Recovery Time	t _{rr2}	V _{CC} =600V I _F =12A		0.12	0.30	0.48	μs
Diode Reverse Recovery Charge	Q _{rr}	-di _F /dt=200A/μs T _J =25°C		0.24	0.60	0.96	μC

■ Equivalent circuit



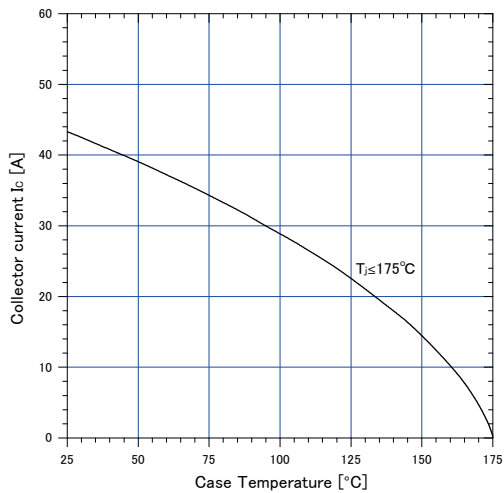
Description	Symbols	Conditions	Characteristics			Unit
			min.	typ.	max.	
Diode Reverse Recovery Time	t_{rr2}	$V_{CC}=600V$ $I_F=12A$	0.22	0.55	0.88	μs
Diode Reverse Recovery Charge	Q_{rr}	$-di_F/dt=200A/\mu s$ $T_J=175^\circ C$	1.2	3.0	4.8	μC

● Thermal resistance

Items	Symbols	Characteristics			Unit
		min.	typ.	max.	
Thermal Resistance, Junction-Ambient	$R_{th(j-a)}$	-	-	50	$^\circ C/W$
Thermal Resistance, IGBT Junction to Case	$R_{th(j-c)}_{IGBT}$	-	-	0.546	
Thermal Resistance, FWD Junction to Case	$R_{th(j-c)}_{FWD}$	-	-	1.923	

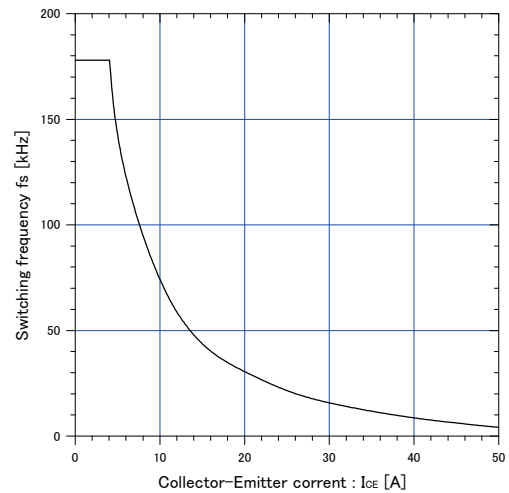
■ Characteristics (Representative)

Graph.1

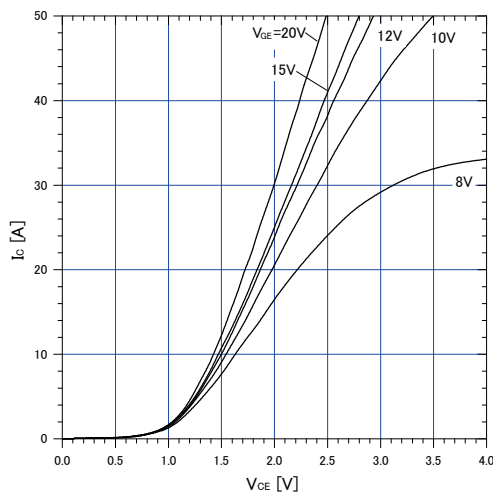
DC Collector Current vs T_c $V_{GE} \geq +15V$, $T_J \leq 175^\circ C$ 

Graph.2

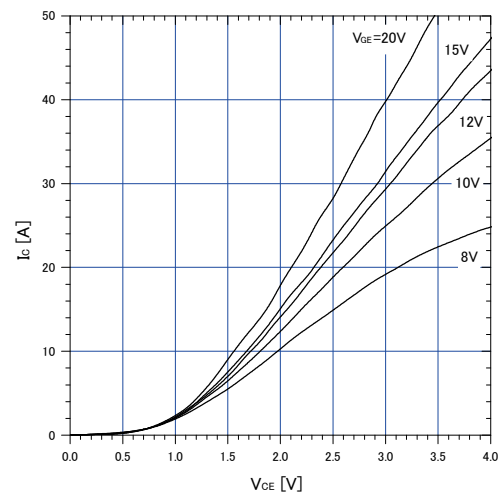
Collector Current vs. switching frequency

 $V_{GE} = +15V$, $T_c \leq 175^\circ C$, $V_{CE} = 600V$, $D = 0.5$, $R_g = 10\Omega$, $T_c = 100^\circ C$ 

Graph.3

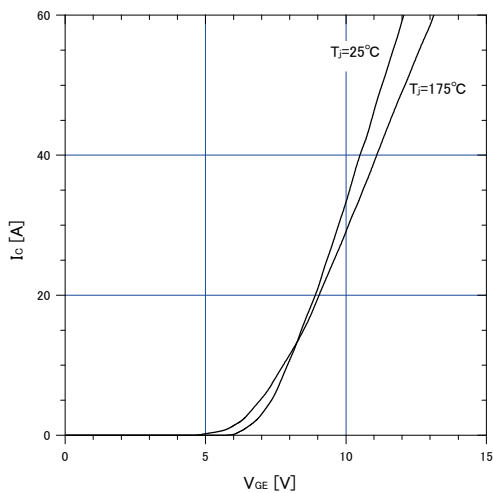
Typical Output Characteristics ($V_{CE} - I_c$) $T_J = 25^\circ C$ 

Graph.4

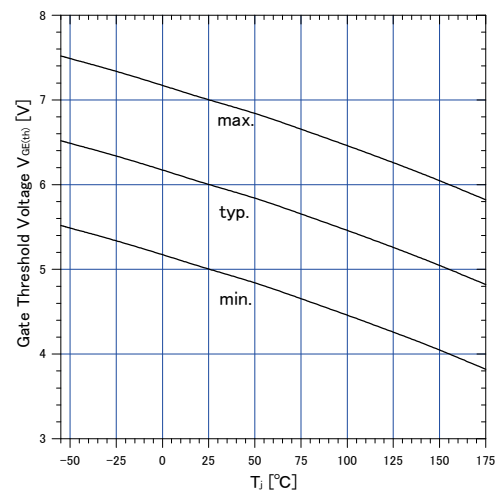
Typical Output Characteristics ($V_{CE} - I_c$) $T_J = 175^\circ C$ 

Graph.5

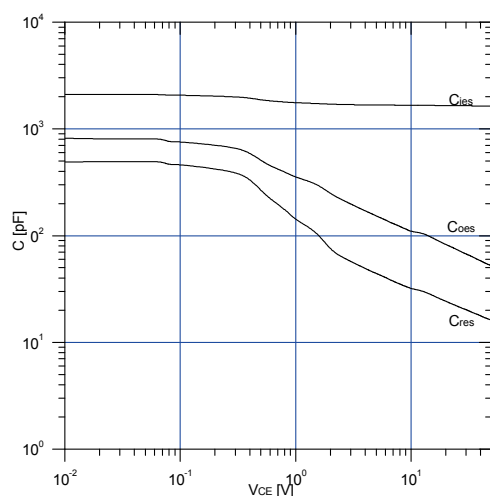
Typical Transfer Characteristics

 $V_{CE} = +15V$ 

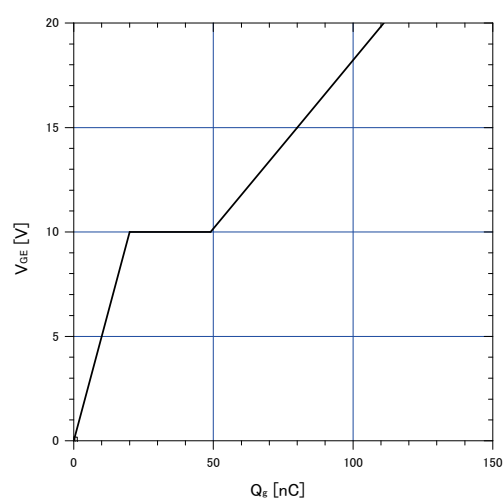
Graph.6

Gate Threshold Voltage vs. T_J $I_c = 25mA$, $V_{CE} = 20V$ 

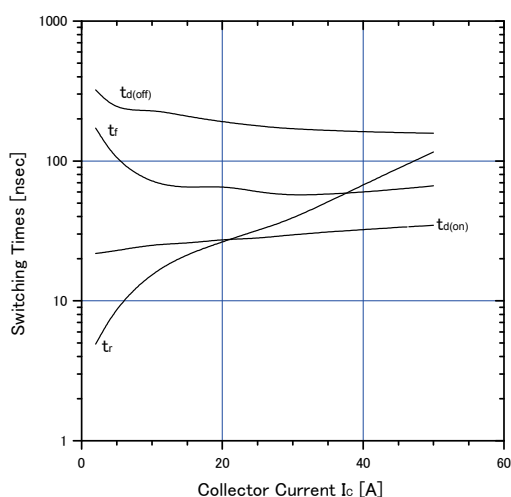
Graph.7
Typical Capacitance
 $V_{GE}=0V$, $f=1MHz$, $T_J=25^\circ C$



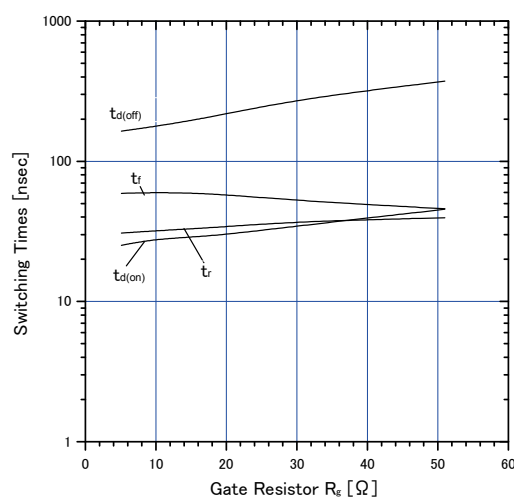
Graph.8
Typical Gate Charge
 $V_{CC}=600V$, $I_C=25A$, $T_J=25^\circ C$



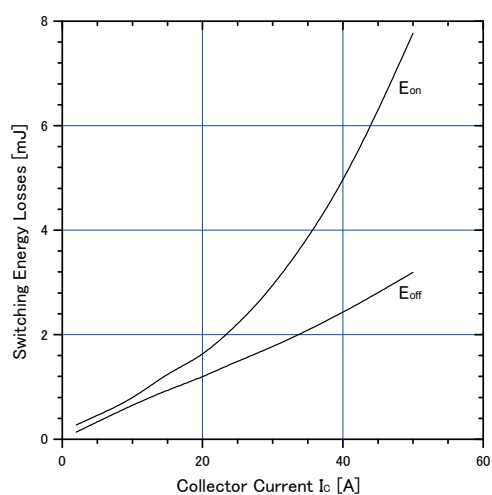
Graph.9
Typical switching time vs. I_C
 $T_J=175^\circ C$, $V_{CC}=600V$, $L=500\mu H$
 $V_{GE}=15V$, $R_G=10\Omega$



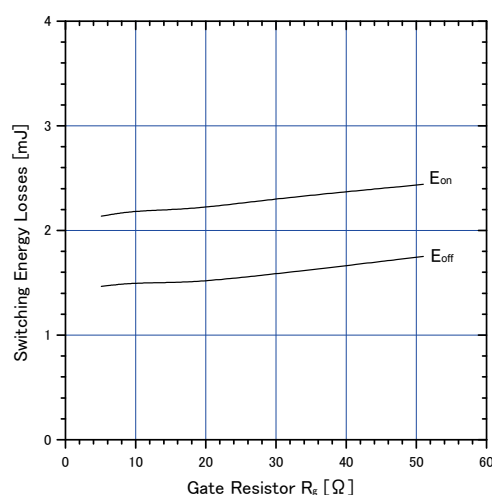
Graph.10
Typical switching time vs. R_G
 $T_J=175^\circ C$, $V_{CC}=600V$, $I_C=25A$, $L=500\mu H$
 $V_{GE}=15V$



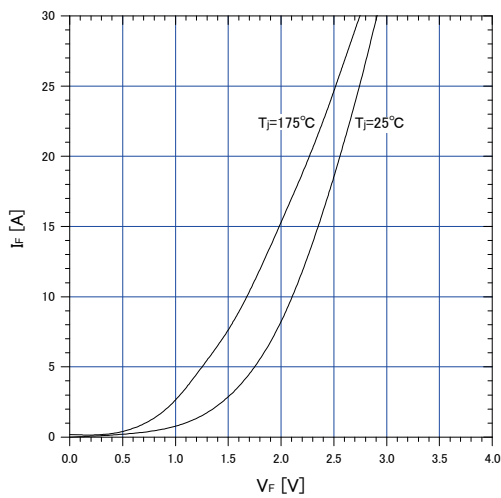
Graph.11
Typical switching losses vs. I_C
 $T_J=175^\circ C$, $V_{CC}=600V$, $L=500\mu H$
 $V_{GE}=15V$, $R_G=10\Omega$



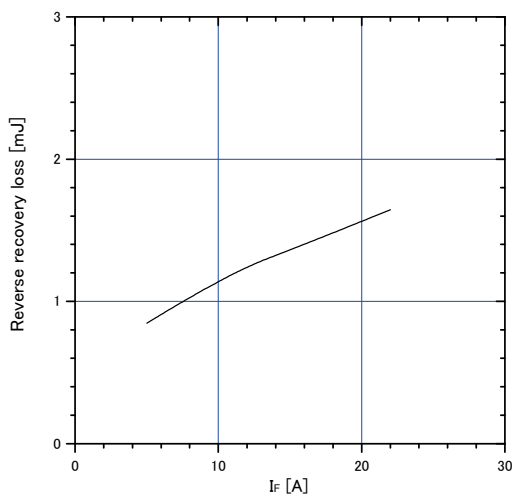
Graph.12
Typical switching losses vs. R_G
 $T_J=175^\circ C$, $V_{CC}=600V$, $I_C=40A$, $L=500\mu H$
 $V_{GE}=15V$



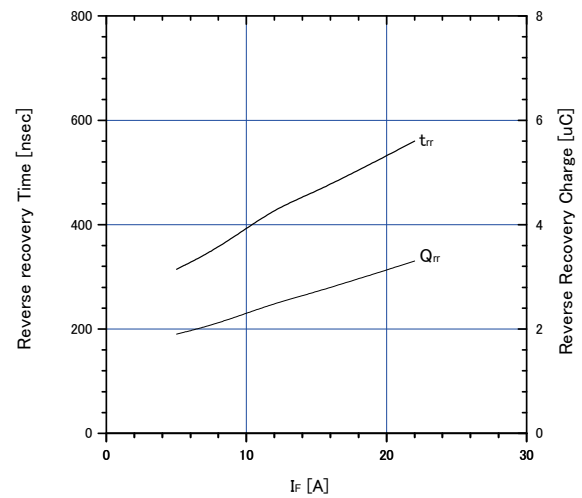
Graph.13
FWD Forward voltage drop (V_F - I_F)



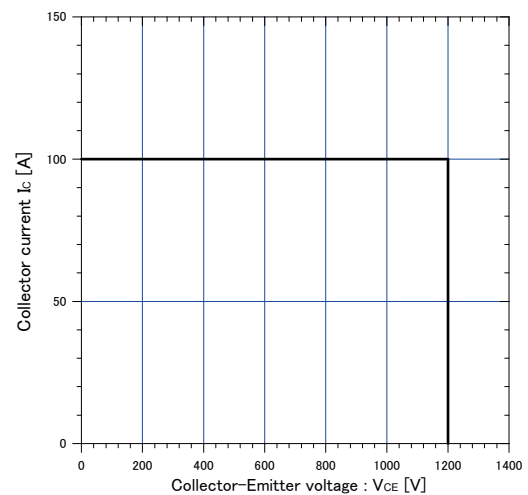
Graph.15
Typical reverse recovery loss vs. I_F
 $T_J = 175^\circ\text{C}$, $V_{CC} = 600\text{V}$, $L = 500\mu\text{H}$
 $V_{GE} = 15\text{V}$, $R_G = 10\Omega$



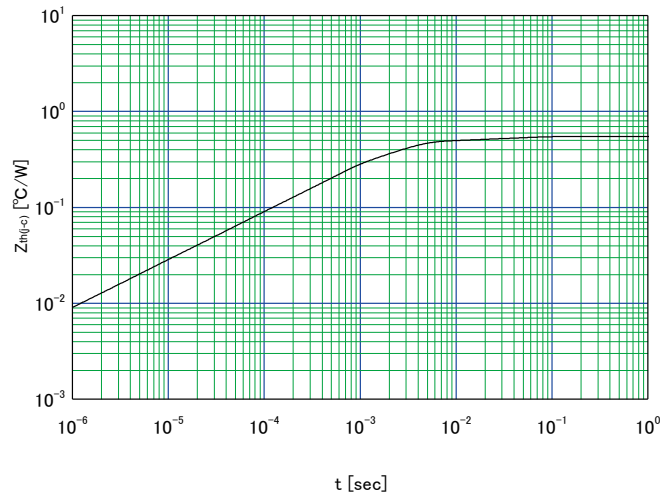
Graph.14
Typical reverse recovery characteristics vs. I_F
 $T_J = 175^\circ\text{C}$, $V_{CC} = 600\text{V}$, $L = 500\mu\text{H}$,
 $V_{GE} = 15\text{V}$, $R_G = 10\Omega$



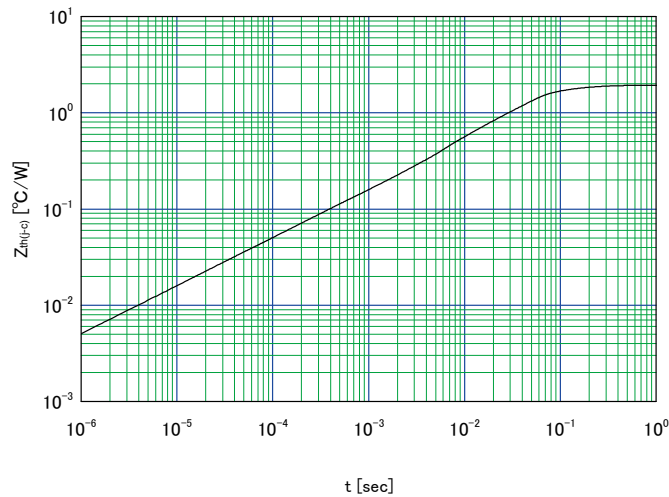
Graph.16
Reverse biased Safe Operating Area
 $T_J \leq 175^\circ\text{C}$, $V_{GE} = +15\text{V}/0\text{V}$, $R_G = 10\Omega$



Graph.17
Transient thermal resistance of IGBT

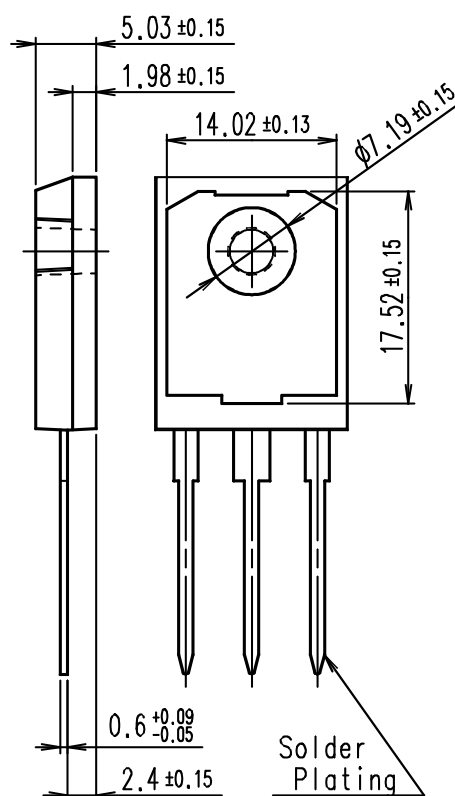
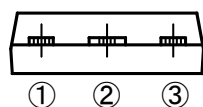
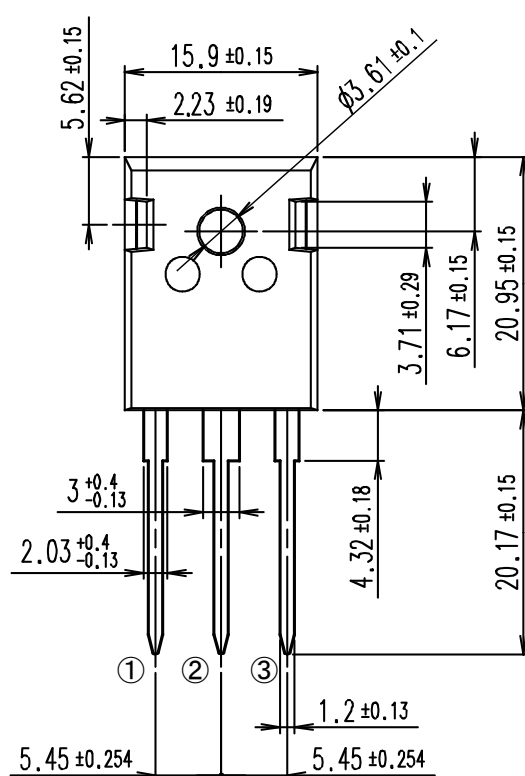


Graph.18
Transient thermal resistance of FWD



■ Outline Drawings, mm

Outview : TO-247 Package



CONNECTION

① GATE

② COLLECTOR

③ EMITTER

DIMENSIONS ARE IN MILLIMETERS.

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